

# TSA82N30M/TSK82N30M

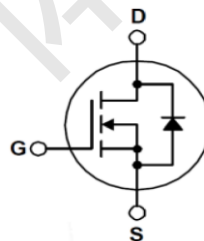
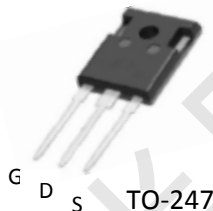
## 300V N-Channel MOSFET

### General Description

This Power MOSFET is produced using Truesemi's advanced planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high power inverter, cutting machine.

### Features

- 82A, 300V, Max.  $R_{DS(on)} = 46m\Omega$  @  $V_{GS} = 10V$
- Low gate charge:  $Q_g = 140nC$  (Typ.)
- 100% avalanche tested
- RoHS compliant device



### Absolute Maximum Ratings $T_c = 25^\circ C$ unless otherwise specified

Symbol	Parameter	Value	Units
$V_{DSS}$	Drain-Source Voltage	300	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current	$T_c = 25^\circ C$	82
		$T_c = 100^\circ C$	52
$I_{DM}$	Pulsed Drain Current (Note 1)	328	A
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	3675	mJ
$I_{AS}$	Repetitive avalanche current (Note 2)	35	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	19.80	mJ
$P_D$	Power Dissipation ( $T_c = 25^\circ C$ )	198	W
$T_J$	Junction temperature	150	$^\circ C$
$T_{stg}$	Storage temperature range	-55~150	$^\circ C$

### Thermal Resistance Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	0.63	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	62.50	$^\circ C/W$

**Electrical Characteristics**  $T_c=25\text{ }^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**On Characteristics**

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	3.0	--	5.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 41\text{ A}$	--	39.7	46.0	m $\Omega$

**Off Characteristics**

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	300	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=300\text{V}, V_{GS} = 0\text{ V}$	--	--	25	$\mu\text{A}$
		$V_{DS} = 300\text{ V}, T_c = 125\text{ }^\circ\text{C}$	--	--	100	$\mu\text{A}$
$I_{GSS}$	Gate leakage current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	--	--	$\pm 100$	nA
$R_g$	Internal gate resistance	Open drain, $f=1\text{MHz}$	--	1	--	$\Omega$

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	6869	--	pF
$C_{oss}$	Output Capacitance		--	737	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	86	--	pF

**Switching Characteristics**

$t_{d(on)}$	Turn-On Time	$V_{DD}=150\text{V}, I_D=82\text{A},$ $R_G=25\Omega$ (Note 3,4)	--	110	--	ns	
$t_r$	Turn-On Rise Time		--	55	--	ns	
$t_{d(off)}$	Turn-Off Delay Time		--	274	--	ns	
$t_f$	Turn-Off Fall Time		--	52	--	ns	
$Q_g$	Total Gate Charge		$V_{DS}=300\text{V}, V_{GS}=10\text{V},$ $I_D=82\text{A}$ (Note 3,4)	--	140	--	nC
$Q_{gs}$	Gate-Source Charge			--	40	--	nC
$Q_{gd}$	Gate-Drain Charge			--	56	--	nC

**Source-Drain Diode Ratings and Characteristics (TC=25°C unless otherwise noted)**

$I_S$	Continuous Source-Drain Diode Forward Current		--	--	82	A
$I_{SM}$	Pulsed Source-Drain Diode Forward Current		--	--	328	
$V_{SD}$	Source-Drain Diode Forward Voltage	$I_S = 82\text{ A}, V_{GS} = 0\text{ V}$	--	--	1.5	V
$t_{rr}$	Reverse recovery time (Note 3,4)	$I_S = 82\text{ A}, V_{GS} = 0\text{ V}$ $di_p/dt = -100\text{ A}/\mu\text{s}$	--	416	--	ns
$Q_{rr}$	Reverse recovery charge (Note 3,4)		--	5.2	--	$\mu\text{C}$

**Note:**

1. Repeated rating: Pulse width limited by safe operating area
2.  $L=5\text{mH}, I_{AS}=35\text{A}, V_{DD}=50\text{V}, R_G=25\text{ }\Omega$ , Starting  $T_J=25\text{ }^\circ\text{C}$
3. Pulse test: Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$
4. Essentially independent of operating temperature typical characteristics

Typical Characteristics Curve

Fig. 1  $I_D - V_{DS}$

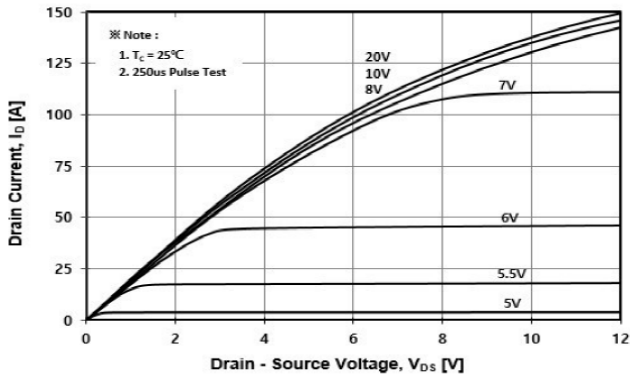


Fig. 2  $I_D - V_{GS}$

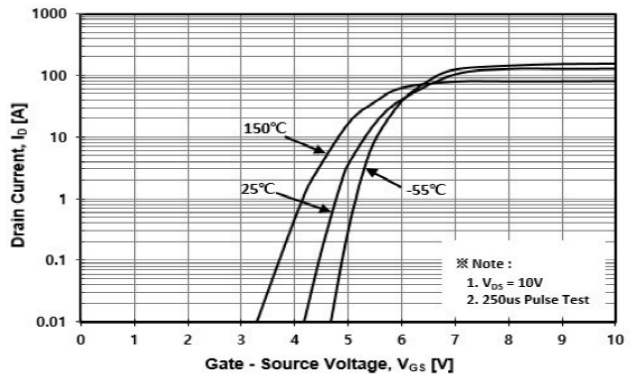


Fig. 3  $R_{DS(ON)} - I_D$

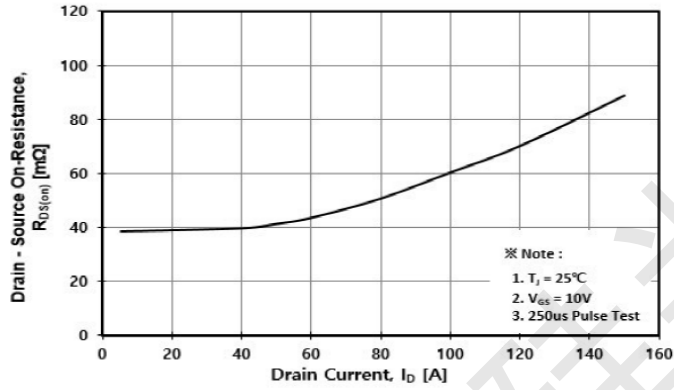


Fig. 4  $I_S - V_{SD}$

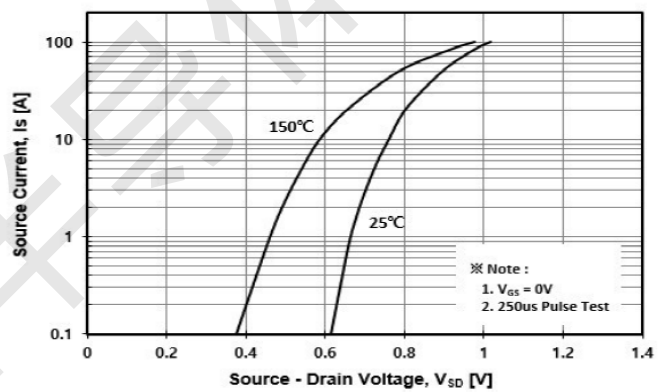


Fig. 5 Capacitance -  $V_{DS}$

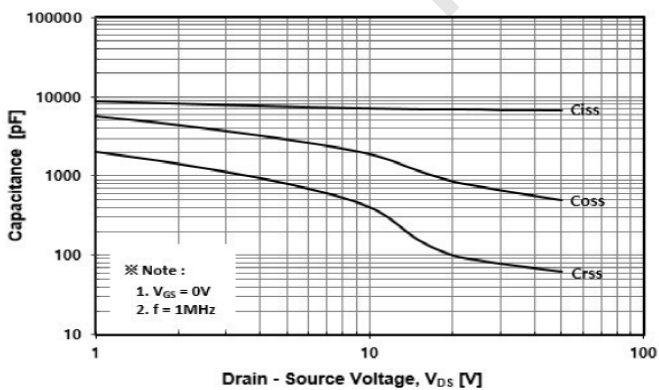
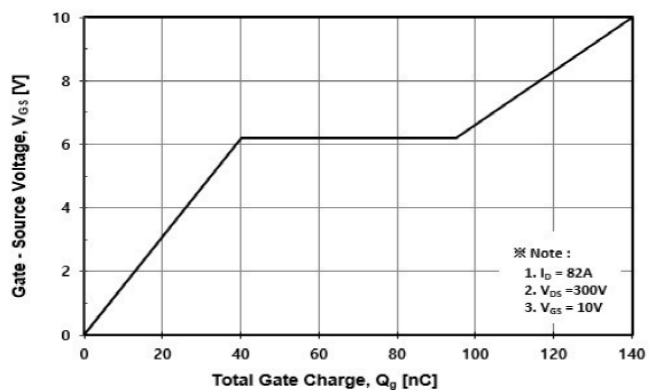


Fig. 6  $V_{GS} - Q_G$



Typical Characteristics Curve (Continue)

Fig. 7  $BV_{DSS} - T_J$

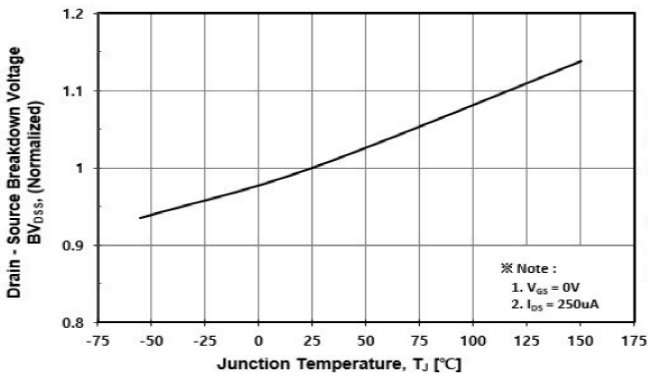


Fig. 8  $R_{DS(ON)} - T_J$

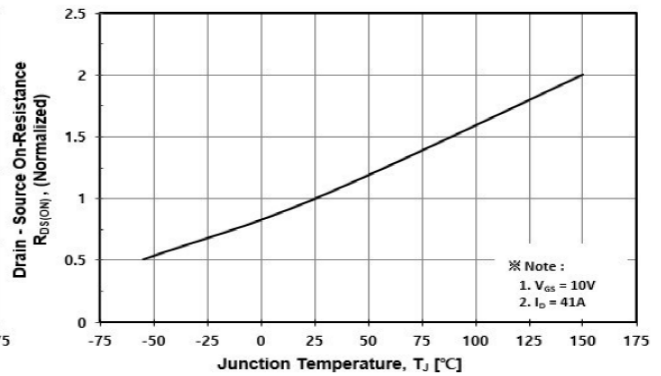


Fig. 9  $I_D - T_C$

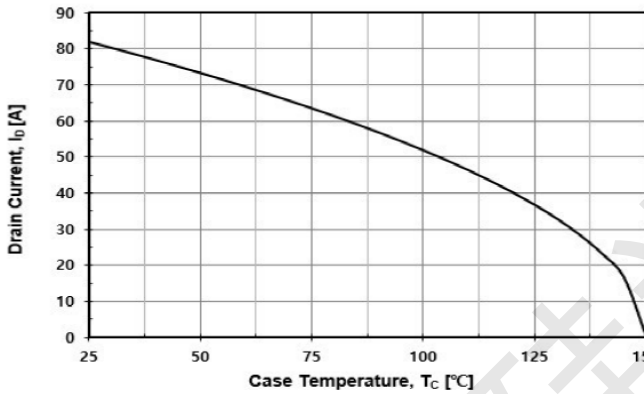


Fig. 10 Safe Operating Area

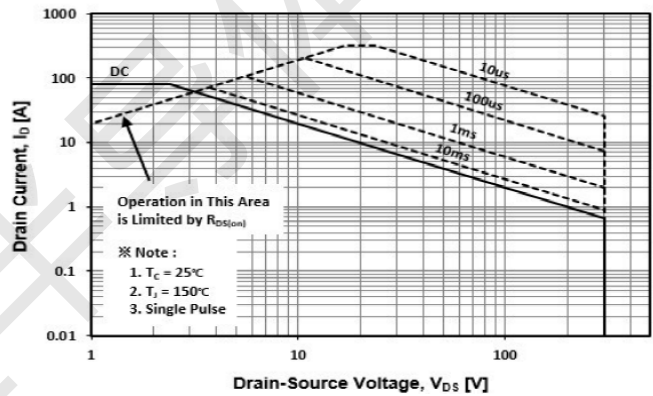


Fig. 11 Transient Thermal Impedance

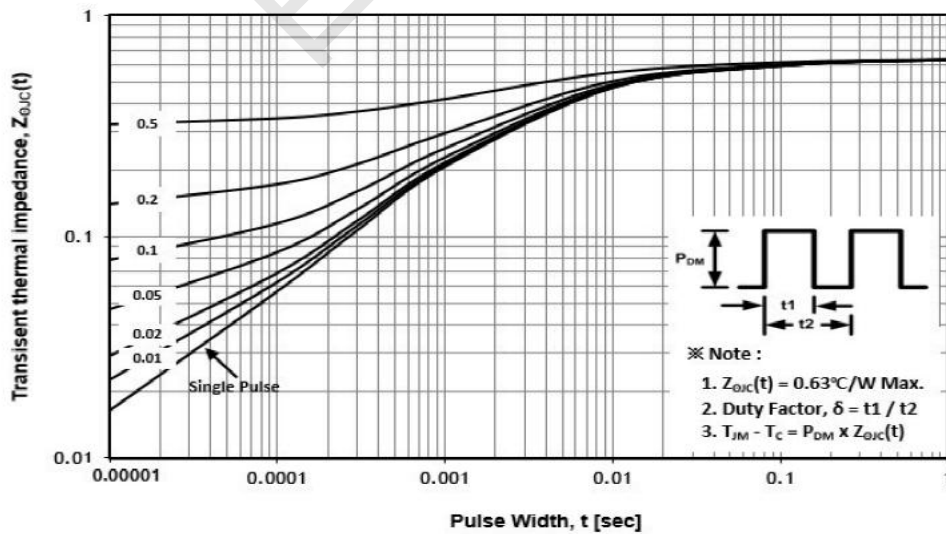


Fig. 12 Gate Charge Test Circuit & Waveform

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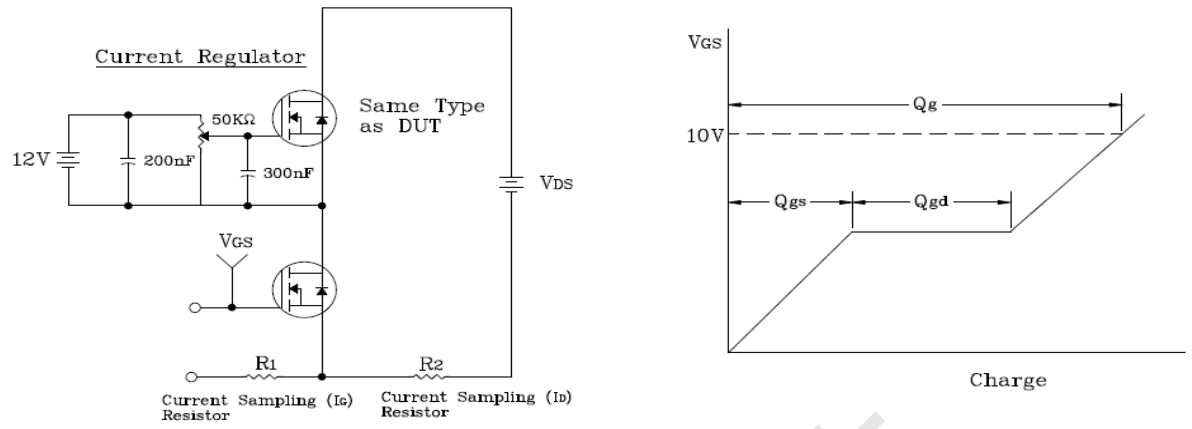


Fig. 13 Resistive Switching Test Circuit & Waveform

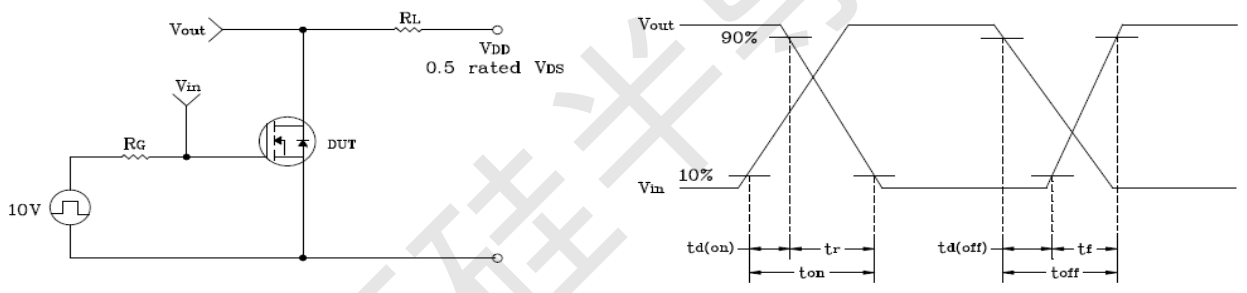


Fig. 14 E<sub>AS</sub> Test Circuit & Waveform

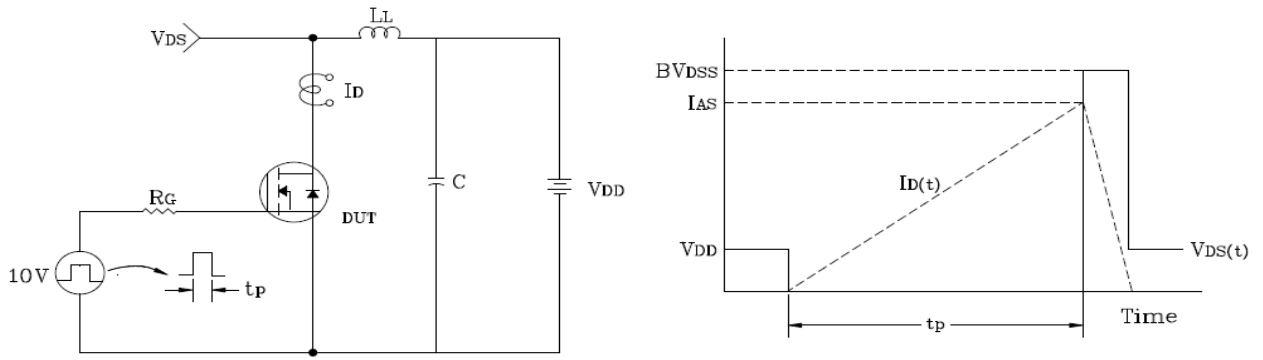


Fig. 15 Diode Reverse Recovery Time Test Circuit & Waveform

